

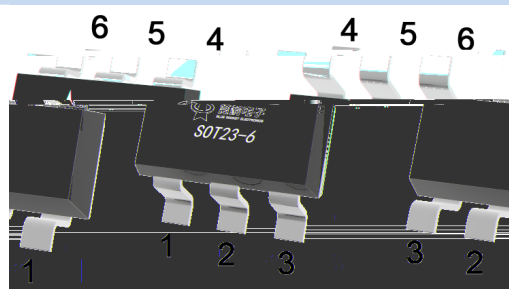
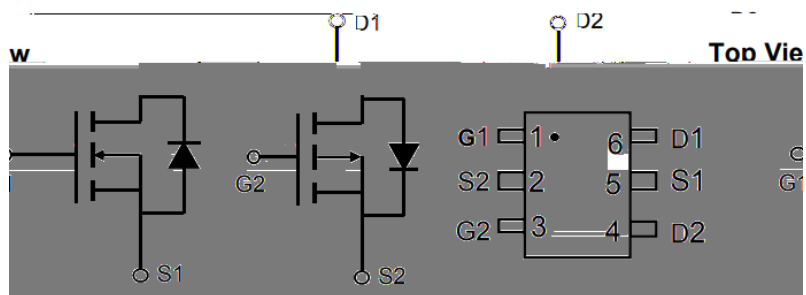
SOT23-6

Complementary Enhancement MOSFET in a SOT23-6 Plastic Package

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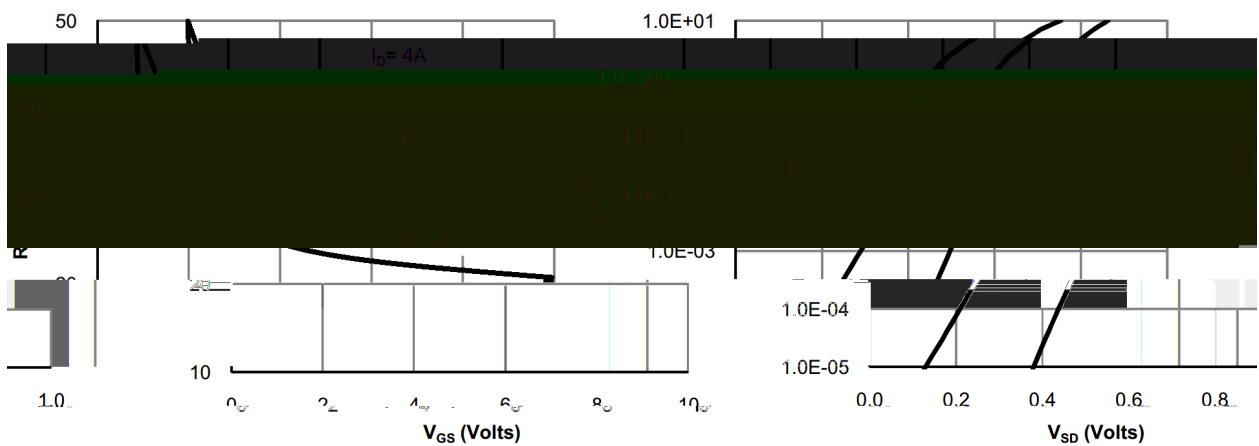
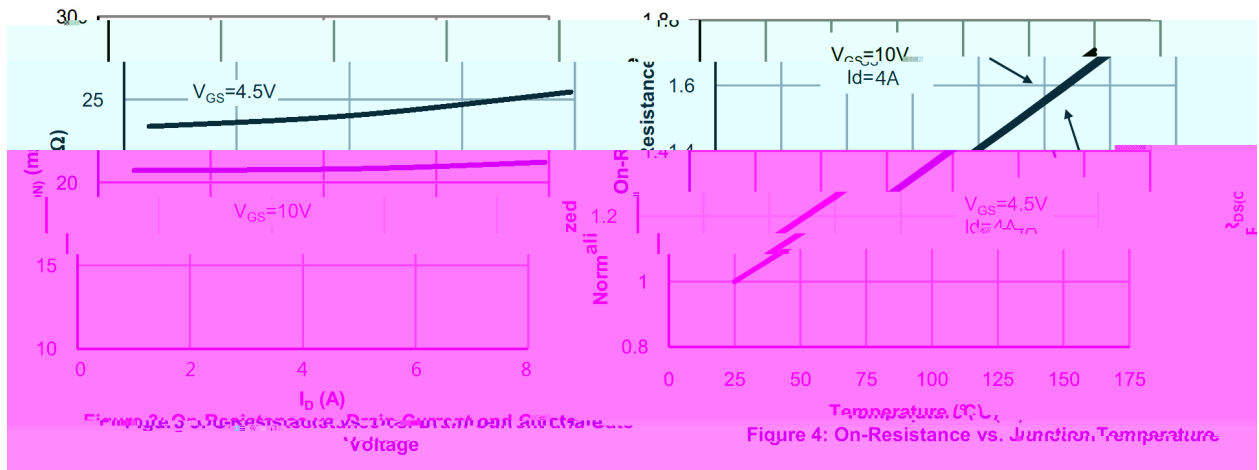
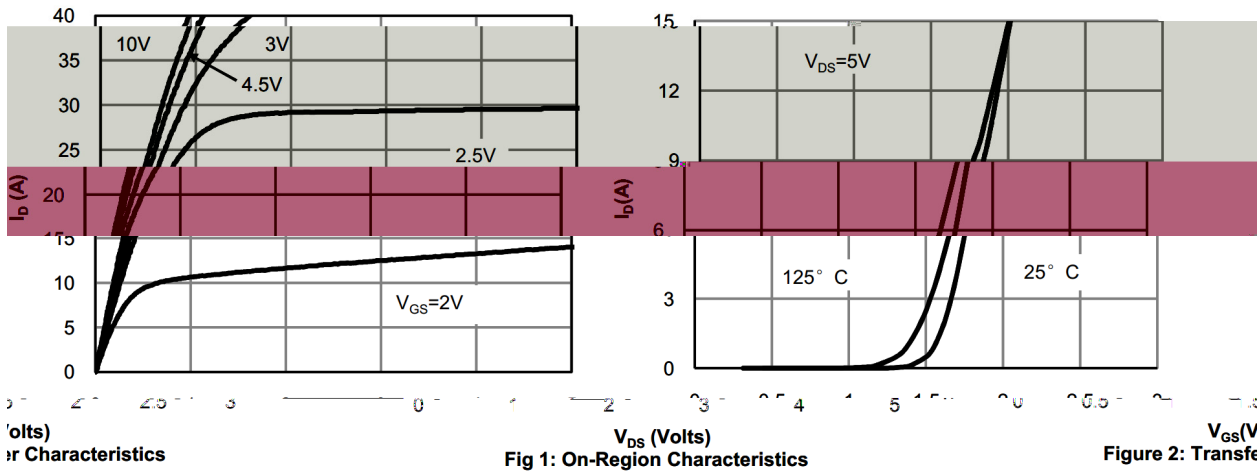


Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristics

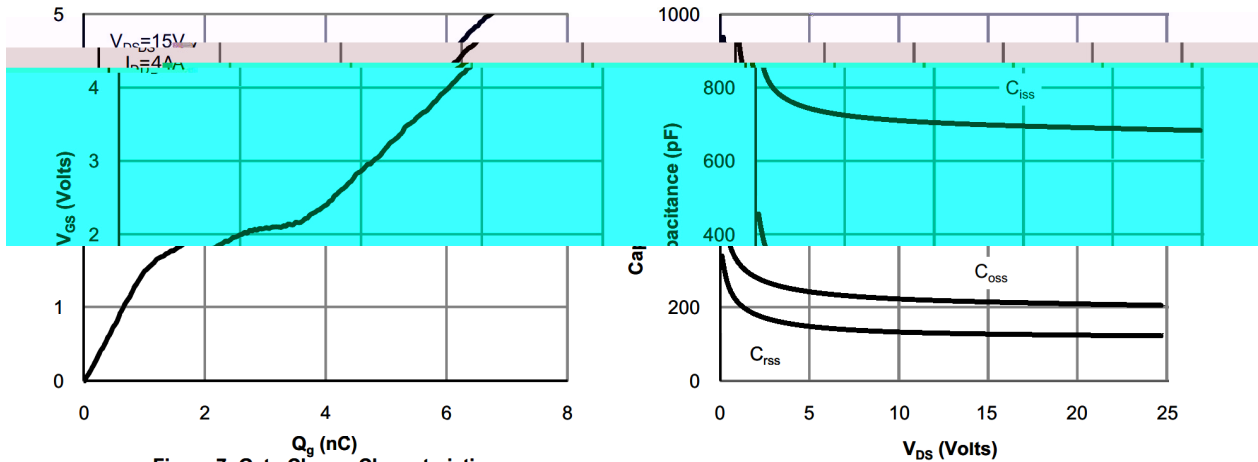


Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

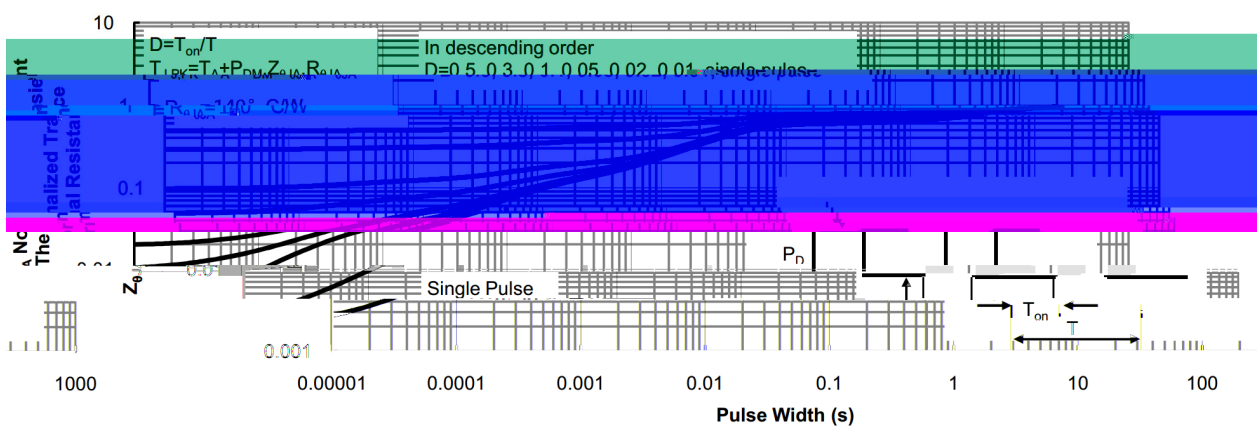
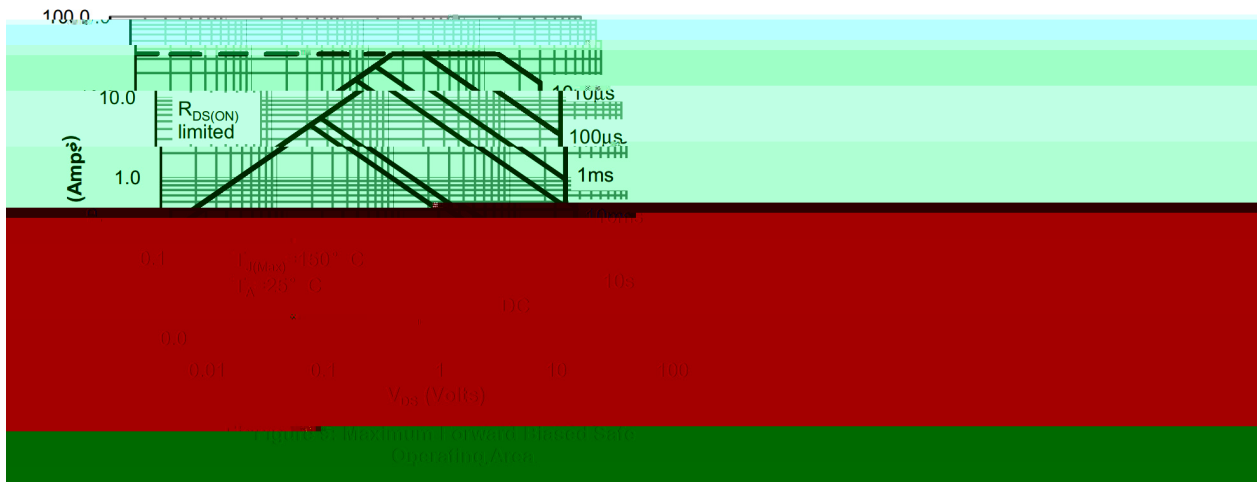
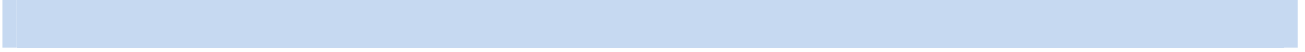


Figure 10: Normalized Maximum Transient Thermal Impedance

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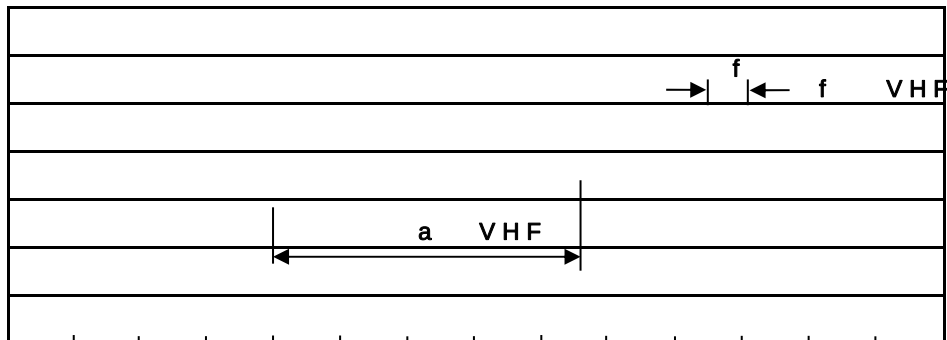
, M y f / Marking Instructions

B01H

^a ¢ y
B01H: ° Z W A
****: ÿ D Z W A k š ÿ D Z J

Note:
B01H y Product Type Code
****: Lot No.Code,code change with Lot No

ŠWD t... • Ž Ć (x /) / : KSVKXGZ[XK 6XULORK LUX /8 8KLRU] 9URJKXOTM 6



7 L P H ` 0 P p 0 8™cp Vx`B 4

^a Ć y

Note:

10• Ä ½ “ † 150 ½180 - k ž • 60 ½90sec;

1.Preheating:150~180 - , Time:60~90sec.

20• Q > “ † 245 r5 - k ž • 4 Ò 5 r0.5sec;

2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.

30•D N ò i Ò 0 , † 2 ½10 - /sec.

3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

“ † y 260 r5 -

ž • y 10 r1 sec.

Temp.:260±5

Time:10±1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type 7>û ~ E	Units ;>û H					Dimension ;>û p . (unit Åmm³)		
	Units/Reel /-	Reels/Inner Box -- /-	Units/Inner Box /-	Inner Boxes/Outer Box - /1ç	Units/Outer Box /1ç	Reel	Inner Box	Outer Boxç
SOT23-5/6	3,000	10	30,000	4	120,000	7 s ×8	210×205×205	445×435×230

„Đ y f / Notices